EAG LABORATORIES

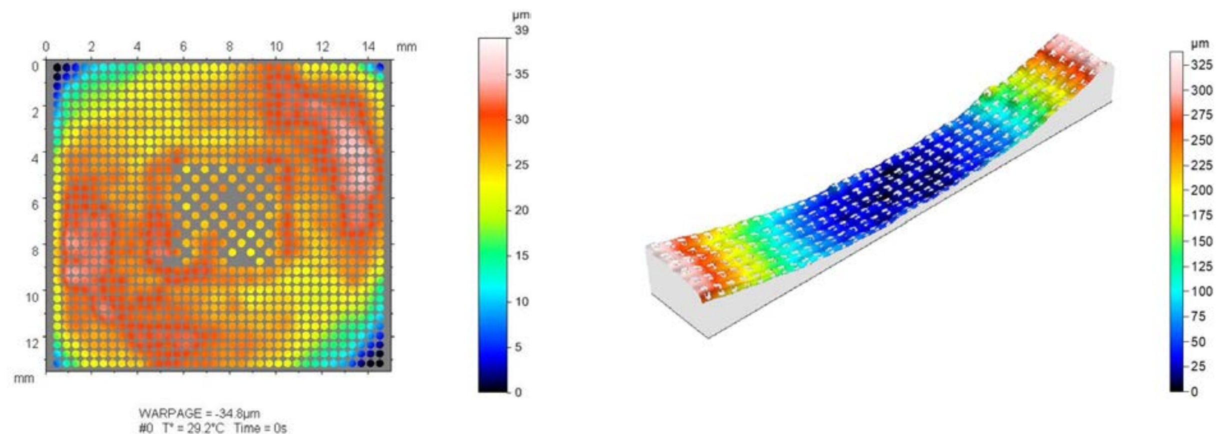
A EUROFINS COMPANY

TDM® by INSIDIX

NEW AT EAG

In-situ warpage & deformation measurements during thermal stresses

- 3D topography measurements over temperature profiles
- Submicron resolution
- Temperature range from -65°C to 400°C using high homogeneity IR and convection sources
- Samples from 0.5x0.5 to 400x500 mm with multiscale FOV
- Able to measure discontinuous surfaces (e.g. multiple components on PCBA)



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Our new service can help at various steps of a product life cycle:

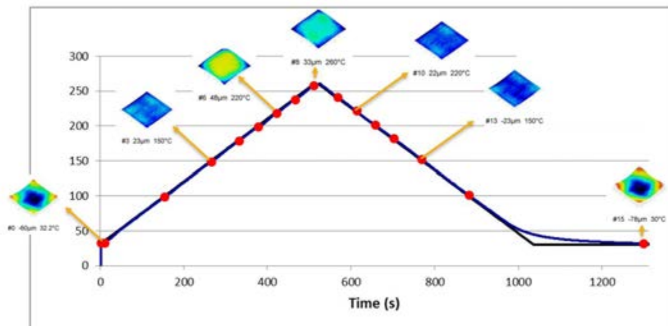
R&D
Process control
Design of manufacturing
Quality control
Failure analysis

Applications
CTE mismatch
Characterization of complex assemblies
Reliability of lead-free solder assemblies
Extreme environment stress
Coplanarity and flatness
Thermal mechanical analysis

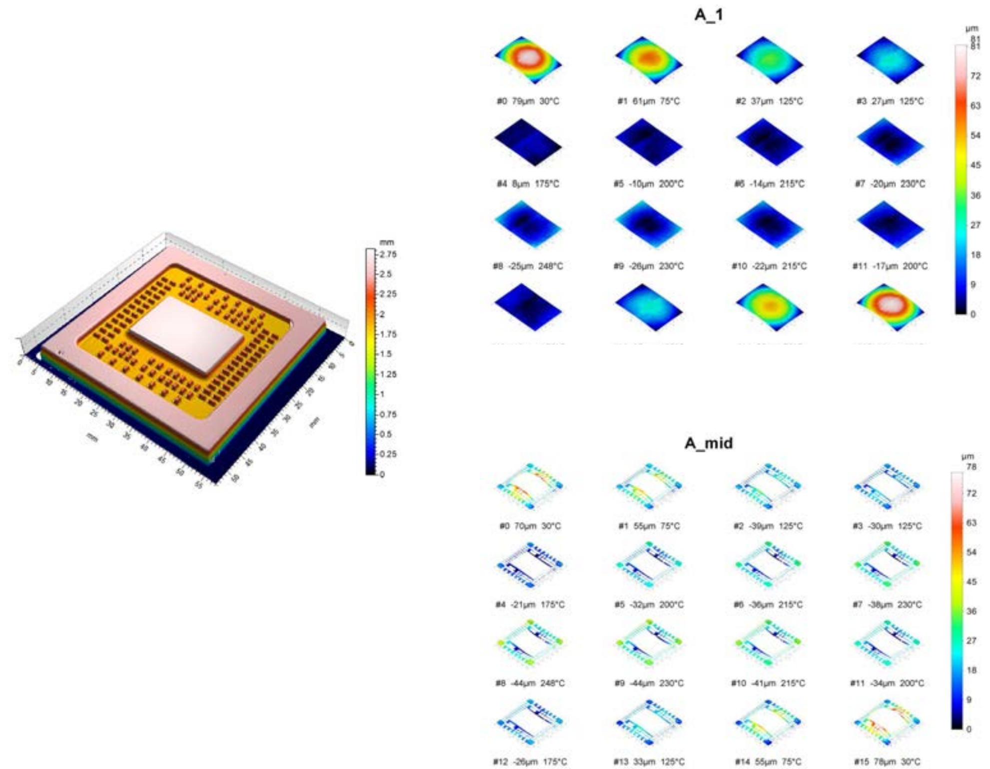
Samples
IC packages (BGA, WLCSP, MCM, PoP, etc.)
Wafers
PCBA
High power devices
Large, complex assemblies
Panels, plates, laminates
Thin film, stacked construction

Industries
Semiconductor
Automotive
Aerospace/Military/Defense
Industrial
Medical device
Consumer Electronics
Manufacturing

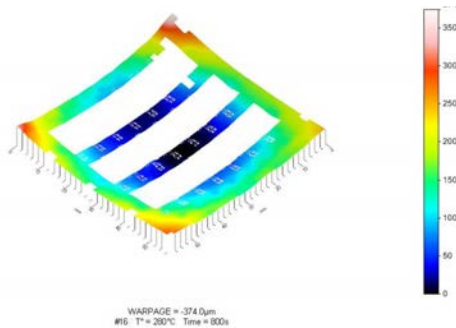
3D Measurements over Temperature Profiles



Multi-Area Analysis



Printed Circuit Board



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